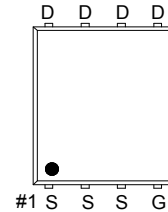
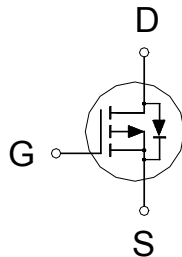


PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D
-30V	7.5mΩ	-30A



1. GATE
2. DRAIN
3. SOURCE

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ °C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±25	V
Continuous Drain Current	$T_C = 25\text{ °C}$ (Package Limited)	I_D	-30	A
	$T_C = 25\text{ °C}$ (Silicon Limited)		-72	
	$T_C = 100\text{ °C}$		-45	
Pulsed Drain Current ¹		I_{DM}	-120	
Continuous Drain Current	$T_A = 25\text{ °C}$	I_D	-14	
	$T_A = 70\text{ °C}$		-11	
Avalanche Current		I_{AS}	-70	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	249	mJ
Power Dissipation	$T_C = 25\text{ °C}$	P_D	62.5	W
	$T_C = 100\text{ °C}$		25	
Power Dissipation	$T_A = 25\text{ °C}$	P_D	2.5	W
	$T_A = 70\text{ °C}$		1.6	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient	$R_{\theta JA}$		50	°C / W
Junction-to-Case	$R_{\theta JC}$		2	

¹Pulse width limited by maximum junction temperature.

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ °C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1	-1.7	-3	

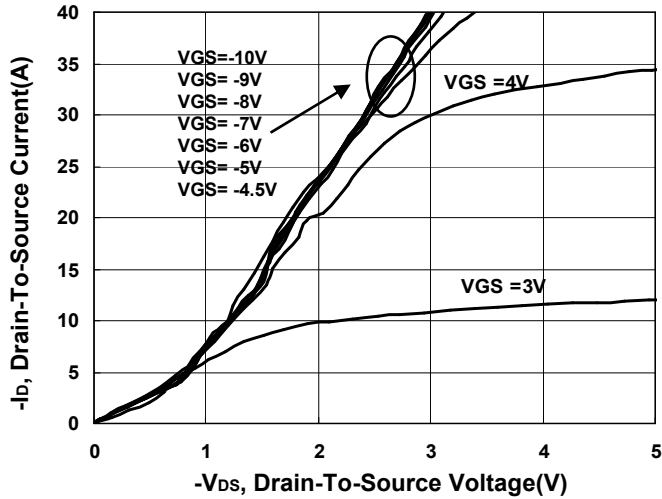
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 25V$			± 250	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -24V, V_{GS} = 0V$			1	μA
		$V_{DS} = -20V, V_{GS} = 0V, T_J = 125^\circ C$			10	
On-State Drain Current ¹	$I_{D(ON)}$	$V_{DS} = -5V, V_{GS} = -10V$	-120			A
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = -4.5V, I_D = -20A$		8	12	$m\Omega$
		$V_{GS} = -10V, I_D = -25A$		5.3	7.5	
Forward Transconductance ¹	g_{fs}	$V_{DS} = -5V, I_D = -25A$		25		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = -15V, f = 1MHz$		5730		pF
Output Capacitance	C_{oss}			911		
Reverse Transfer Capacitance	C_{rss}			679		
Total Gate Charge ²	Q_g	$V_{GS}=10V$	$V_{DS} = 0.5V_{(BR)DSS}, V_{GS} = -10V,$ $I_D = -25A$		120	nC
		$V_{GS}=4.5V$			60	
Gate-Source Charge ²	Q_{gs}			16		
Gate-Drain Charge ²	Q_{gd}			30		
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DS} = -20V,$ $I_D \cong -25A, V_{GS} = -10V, R_{GS} = 6\Omega$			20	
Rise Time ²	t_r			36		
Turn-Off Delay Time ²	$t_{d(off)}$			140		
Fall Time ²	t_f			102		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_J = 25^\circ C$)						
Continuous Current	I_S				-30	A
Forward Voltage ¹	V_{SD}	$I_F = -25A, V_{GS} = 0V$			-1.3	V
Reverse Recovery Time	t_{rr}	$I_F = -25A, di_F/dt = 100A / \mu S$		42		nS
Reverse Recovery Charge	Q_{rr}			30		nC

¹Pulse test : Pulse Width $\leq 300 \mu sec$, Duty Cycle $\leq 2\%$.

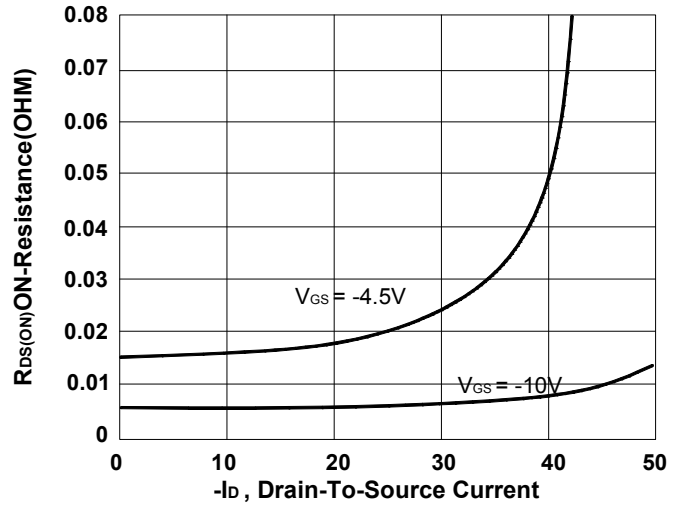
²Independent of operating temperature.

REMARK: THE PRODUCT MARKED WITH "P0703EK", DATE CODE or LOT #

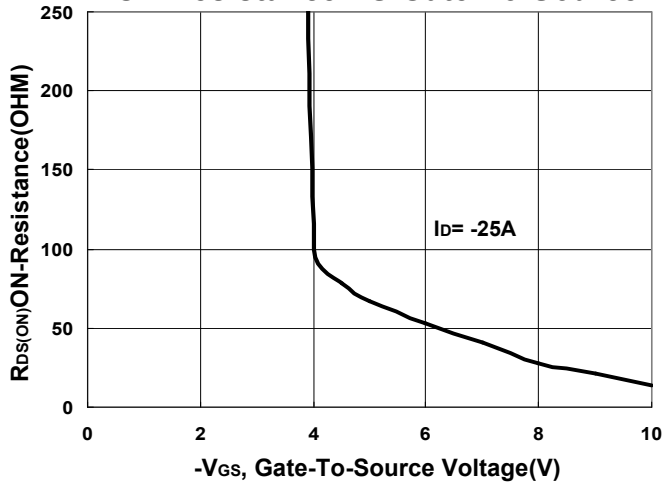
Output Characteristics



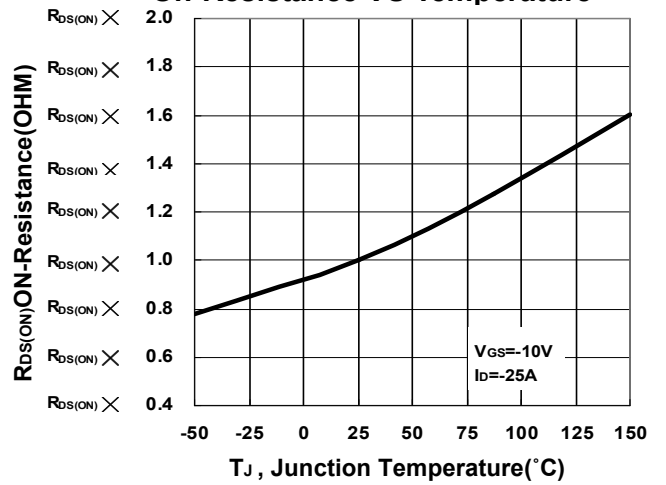
On-Resistance VS Drain Current



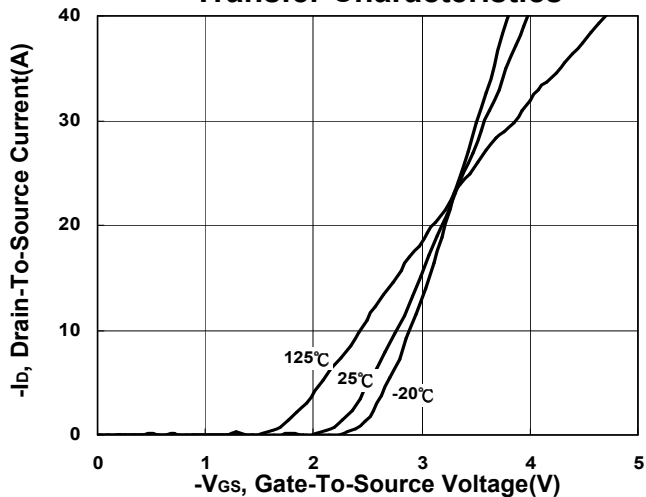
On-Resistance VS Gate-To-Source



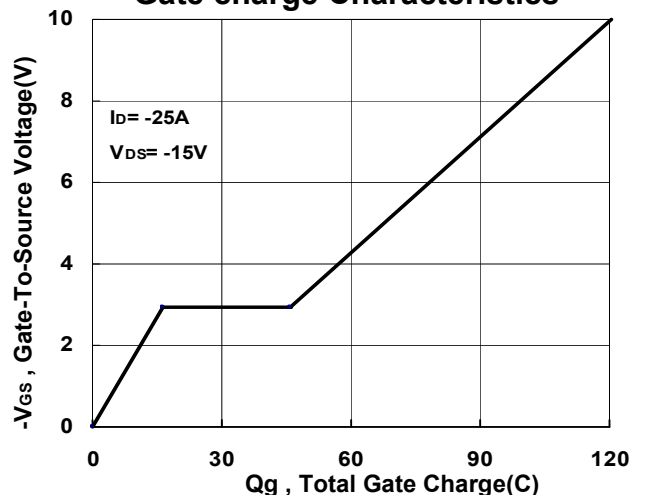
On-Resistance VS Temperature

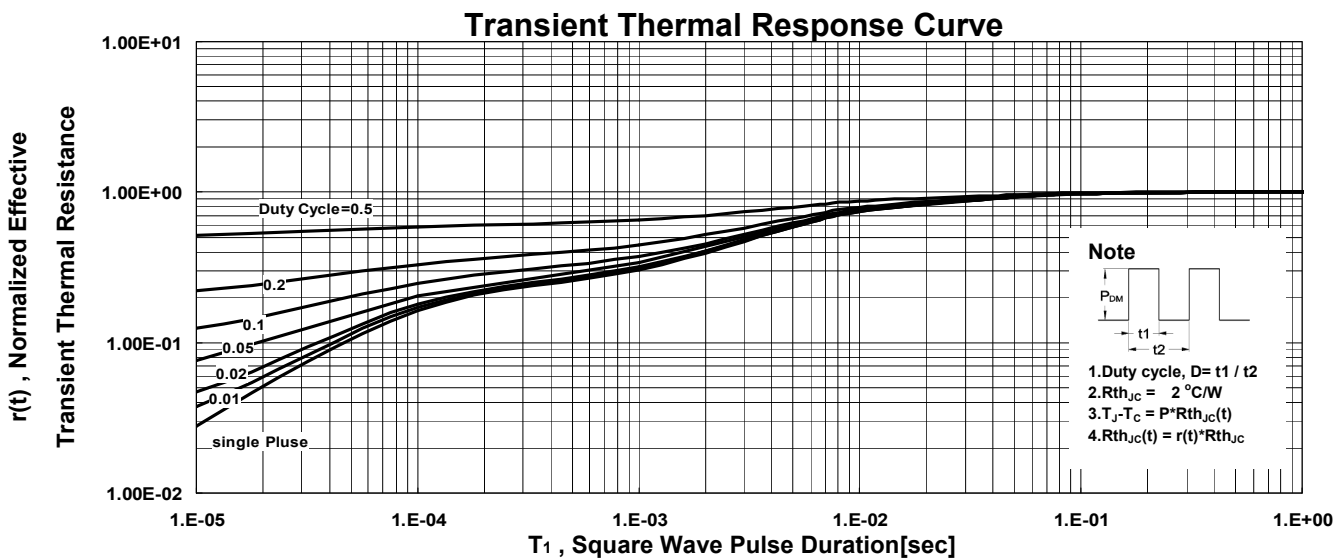
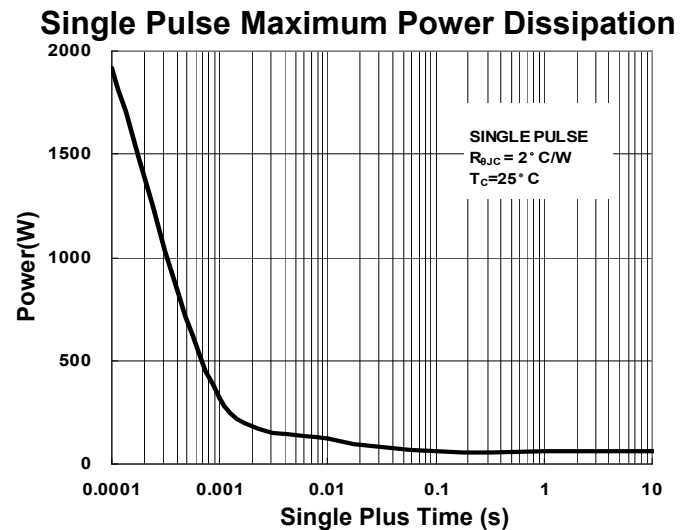
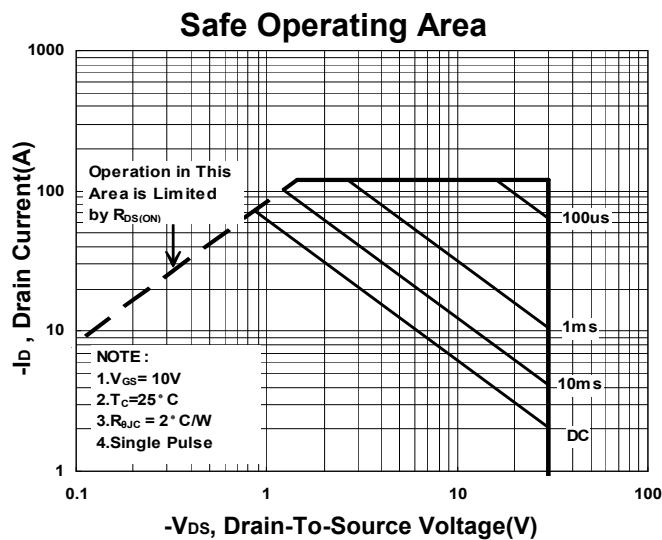
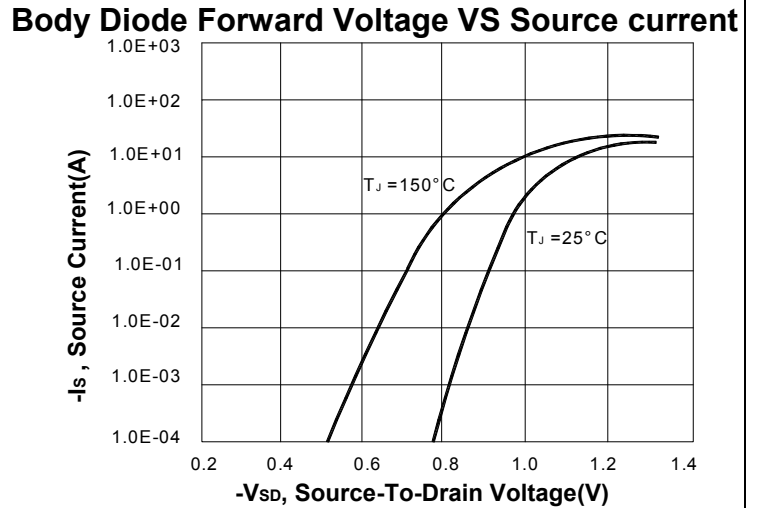
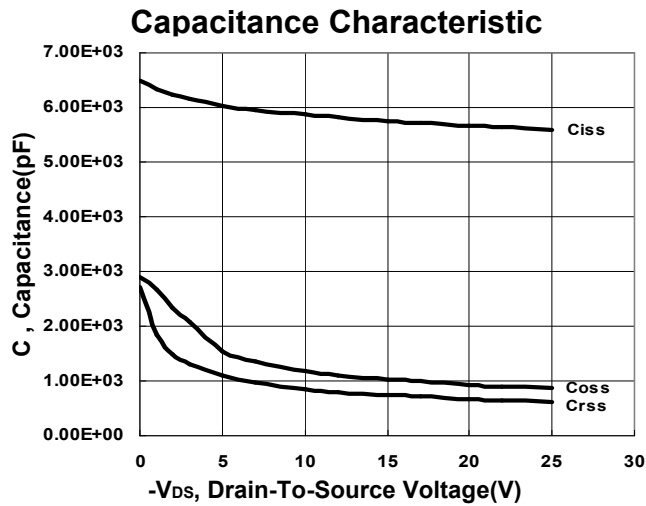


Transfer Characteristics



Gate charge Characteristics





Package Dimension

NPAK 5x6 MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.8	4.9	5.0	I	0.5	0.6	0.7
B	5.7	5.75	5.8	J	3.40	3.60	3.80
C	5.9	6.0	6.1	K	1.1		
D	0.35	0.40	0.45	L	0.50	0.60	0.70
E		1.27		M	8°	10°	12°
F	0.9	1.0	1.1	N			5.1
G	0.2	0.25	0.3	O	0.06	0.13	0.20
H	3.8	3.9	4.0	P			0.1

